What is claimed is:

1. A method for fabricating an anisotropic conductive substrate comprising:

providing a back holder, the back holder having a surface with a plurality of metal pins;

forming a liquid compound on the surface of the back holder with the metal pins;

pressing the liquid compound on the back holder, the liquid compound being reshaped to have an upper surface and a lower surface, the thickness between the upper surface and the lower surface of the liquid compound is between 25 μm and 250 μm, the metal pins being deformed into a plurality of electrodes in the liquid compound and each electrode has an first end and a lower end exposed from the upper surface and the lower surfaces of the liquid compound; and

removing the back holder so that the liquid compound with the electrodes becomes an anistropic conductive substrate.

2. The method for fabricating an anisotropic conductive substrate as claimed in claim 1, wherein the liquid compound is a negative photoresist.

3. The method for fabricating an anisotropic conductive substrate as claimed in claim 1, wherein the liquid compound is a low K dielectric thermosetting material.

4. The method for fabricating an anisotropic conductive substrate as claimed in claim 3, wherein the liquid compound is cured simultaneously during the pressing step.

5. The method for fabricating an anisotropic conductive substrate as claimed in claim 1, wherein a removable layer is formed on the surface of the back holder in the step of providing the back holder.

6. The method for fabricating an anisotropic conductive substrate as claimed in claim 5, wherein the removable layer is a positive photoresist.

7. The method for fabricating an anisotropic conductive substrate as claimed in claim 1, wherein the distribution density of the metal pins is between 10^3 mm^{-2} and 10^8 mm^{-2} in the step of providing the back holder.

8. The method for fabricating an anisotropic conductive substrate as claimed in claim 1,

wherein the pitch between the metal pins is from 0.5 μm to 30 μm.

9. The method for fabricating an anisotropic conductive substrate as claimed in claim 1, further comprising a step of baking the liquid compound prior to the pressing step.

10. The method for fabricating an anisotropic conductive substrate as claimed in claim 1, wherein the liquid compound is transparent.

11. A method for fabricating an anisotropic conductive substrate comprising:

providing a back holder, the back holder having a surface with a plurality of metal pins;

forming a liquid compound on the surface of the back holder with the metal pins;

pressing the liquid compound on the back holder by a top plate and curing the liquid compound simultaneously, the top plate deforming the metal pins into a plurality of electrodes in the liquid compound; and

removing the back holder so that the liquid compound with the electrodes becomes an anistropic conductive substrate.

12. The method for fabricating an anisotropic conductive substrate as claimed in claim 11, wherein the liquid compound is a negative photoresist.

13. The method for fabricating an anisotropic conductive substrate as claimed in claim 11, wherein the liquid compound is transparent.

14. The method for fabricating an anisotropic conductive substrate as claimed in claim 11, wherein a removable layer is formed between the metal pins and the back holder in the step of providing the back holder.

15. The method for fabricating an anisotropic conductive substrate as claimed in claim 14, wherein the removable layer is a positive photoresist.